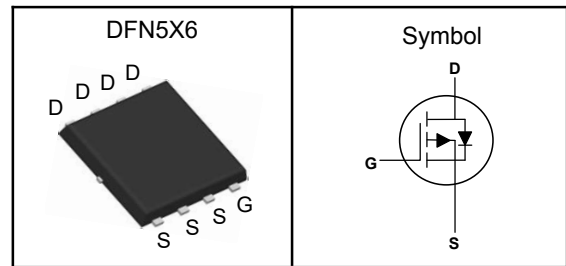


P-Channel Enhancement Mode MOSFET
Features

- Fast switching speed
- ROHS Compliant & Halogen-Free
- 100% UIS and Rg Tested

Applications

- Motor drivers
- DC - DC Converter

Pin Description


V_{DSS}	-30	V
$R_{DS(ON)-Typ}$	2.5	m Ω
I_D	-115	A

Absolute Maximum Ratings ($T_J=25^\circ\text{C}$, Unless Otherwise Noted)

Symbol	Parameter	Rating	Unit
V_{DSS}	Drain-Source Voltage	-30	V
V_{GSS}	Gate-Source Voltage	± 20	V
T_J	Maximum Junction Temperature	-55 to 150	$^\circ\text{C}$
T_{STG}	Storage Temperature Range	-55 to 150	$^\circ\text{C}$
$I_{DM}^{①}$	Pulse Drain Current Tested	-460	A
I_D	Continuous Drain Current	$T_C=25^\circ\text{C}$ -115	A
P_D	Maximum Power Dissipation	$T_C=25^\circ\text{C}$ 80	W
E_{AS}	Avalanche Energy, Single pulse	175	mJ

Thermal Characteristics

Symbol	Parameter	Rating	Unit
$R_{\theta JA}$	Thermal Resistance-Junction to Ambient	62.5	$^\circ\text{C}/\text{W}$
$R_{\theta JC}$	Thermal Resistance-Junction to Case	1.56	$^\circ\text{C}/\text{W}$

Note ① : Max. current is limited by bonding wire.

Note ② : UIS tested and pulse width are limited by maximum junction temperature 150 $^\circ\text{C}$.

Note ③ : Surface Mounted on 1in² FR-4 board with 1oz.



P-Channel Enhancement Mode MOSFET

Electrical Characteristics ($T_J=25^{\circ}\text{C}$, Unless Otherwise Noted)

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
Static Electrical Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=-250\mu A$	-30	---	---	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=-30V, V_{GS}=0V$	---	---	-1	μA
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=-250\mu A$	-1.3	---	-2.1	V
I_{GSS}	Gate Leakage Current	$V_{GS}=\pm 20V, V_{DS}=0V$	---	---	± 100	nA
$R_{DS(on)}$	Drain-Source On-state Resistance	$V_{GS}=-10V, I_D=-20A$	---	2.5	3	$m\Omega$
		$V_{GS}=-4.5V, I_D=-10A$	---	3.5	4.2	$m\Omega$
Dynamic Characteristics^⑤						
C_{iss}	Input Capacitance	$V_{GS}=0V, V_{DS}=-15V, \text{Freq.}=1\text{MHz}$	---	9148	---	pF
C_{oss}	Output Capacitance		---	1173	---	
C_{rss}	Reverse Transfer Capacitance		---	1184	---	
$T_{d(on)}$	Turn-on Delay Time	$V_{GS}=-10V, V_{DS}=-15V, I_D=-10A, R_G=3\Omega$	---	15	---	nS
T_r	Turn-on Rise Time		---	18	---	
$T_{d(off)}$	Turn-off Delay Time		---	110	---	
T_f	Turn-off Fall Time		---	85	---	
Q_g	Total Gate Charge	$V_{GS}=-10V, V_{DS}=-15V, I_D=-5A$	---	177	---	nC
Q_{gs}	Gate-Source Charge		---	23	---	
Q_{gd}	Gate-Drain Charge		---	39	---	
Source-Drain Characteristics						
$V_{SD}^{④}$	Diode Forward Voltage	$I_S=-15A, V_{GS}=0V$	---	---	-1.2	V

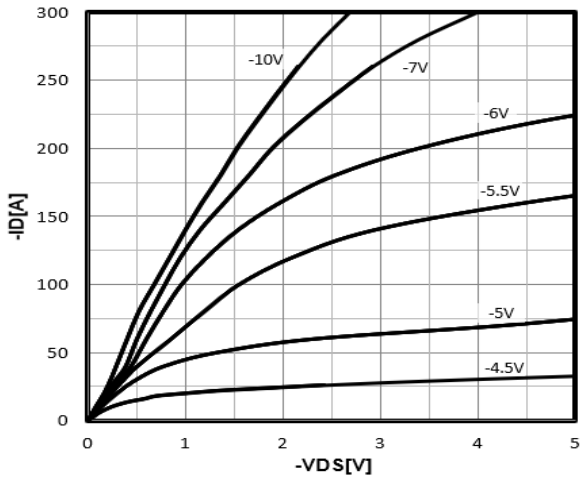
Note ④: Pulse test (pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$).

Note ⑤: Guaranteed by design, not subject to production testing.

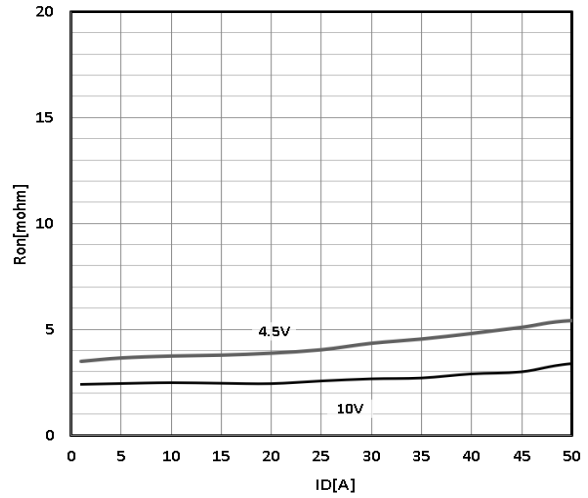


P-Channel Enhancement Mode MOSFET

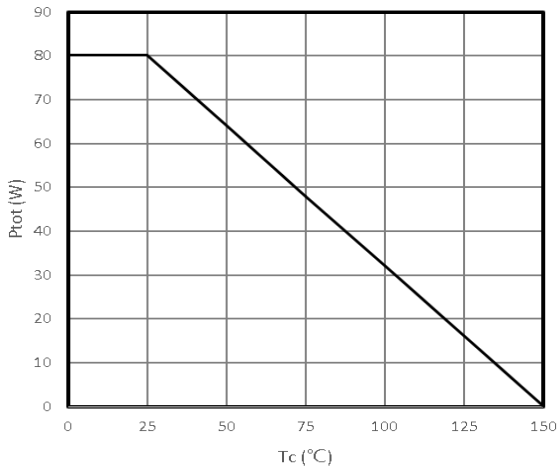
Typical Characteristics



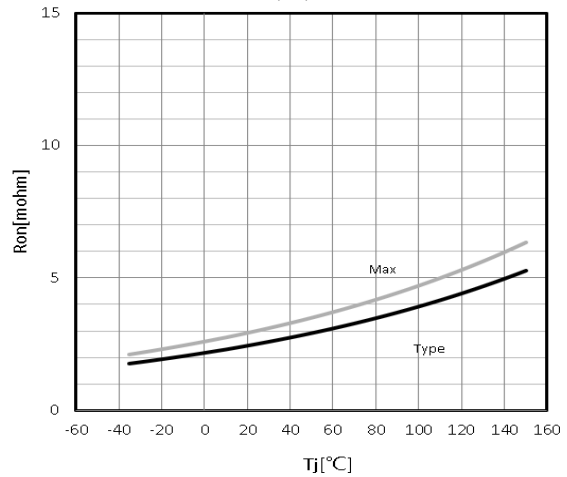
Typ. output characteristics
 $-I_D=f(-V_{DS})$



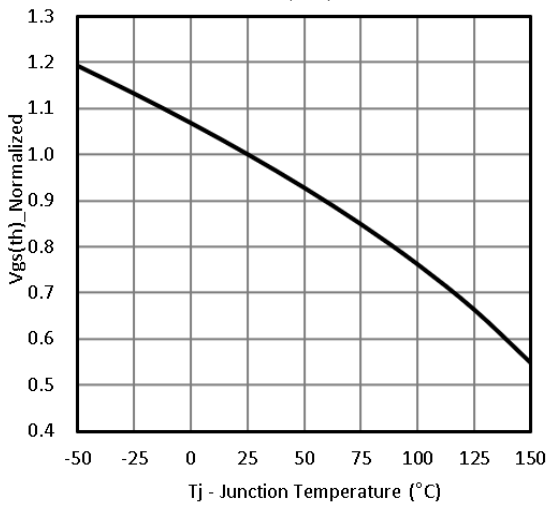
Typ. drain-source on resistance
 $R_{DS(on)}=f(-I_D)$



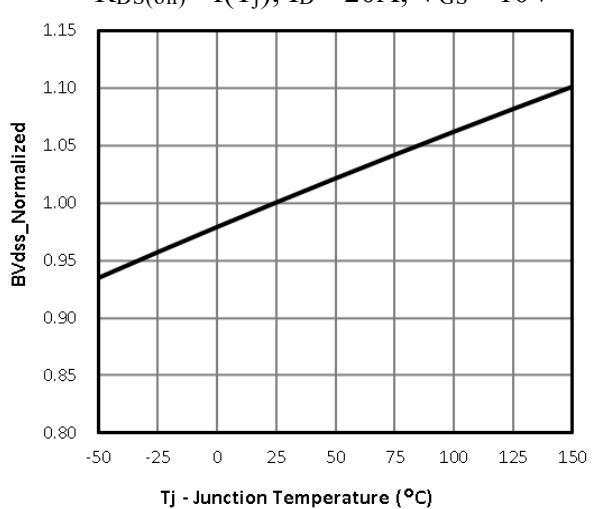
Power Dissipation
 $P_{tot}=f(T_c)$



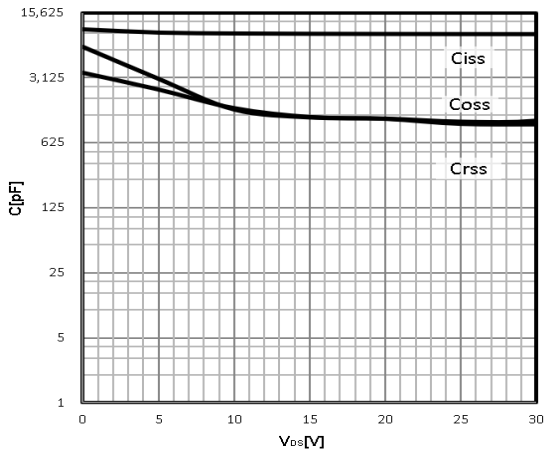
Drain-source on-state resistance
 $R_{DS(on)}=f(T_j); I_D=-20A; V_{GS}=-10V$



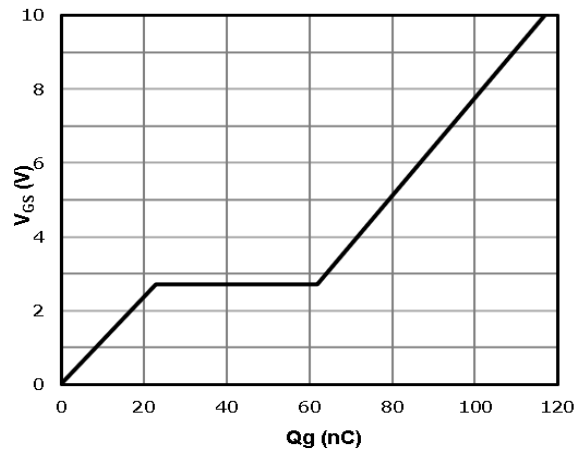
Gate Threshold Voltage
 $-V_{TH}=f(T_j); I_D=-250\mu A$



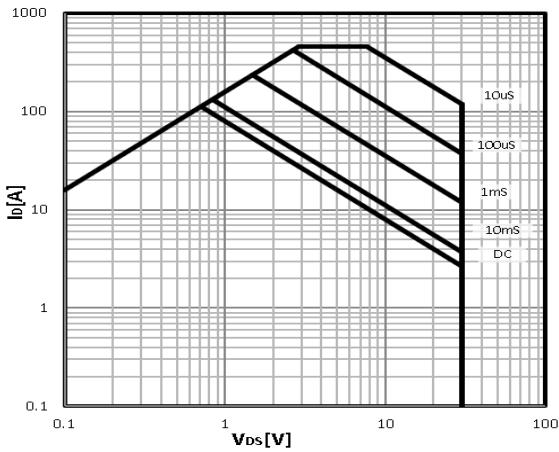
Drain-source breakdown voltage
 $-V_{BR(DSS)}=f(T_j); I_D=-250\mu A$

P-Channel Enhancement Mode MOSFET


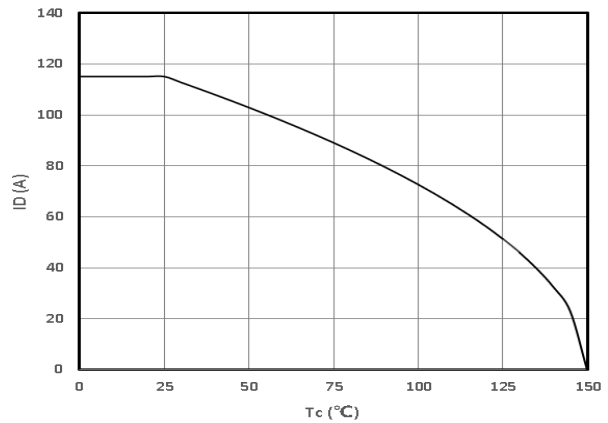
Typ. capacitances
 $C = f(-V_{DS}); V_{GS}=0V; f=1MHz$



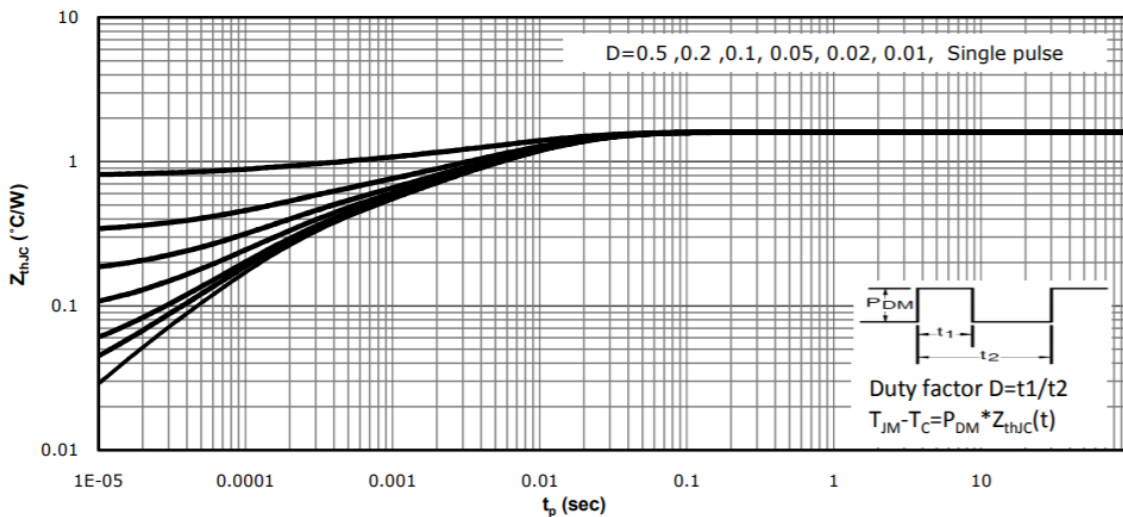
Typ. gate charge
 $-V_{GS}=f(Q_g); I_D=-5A$



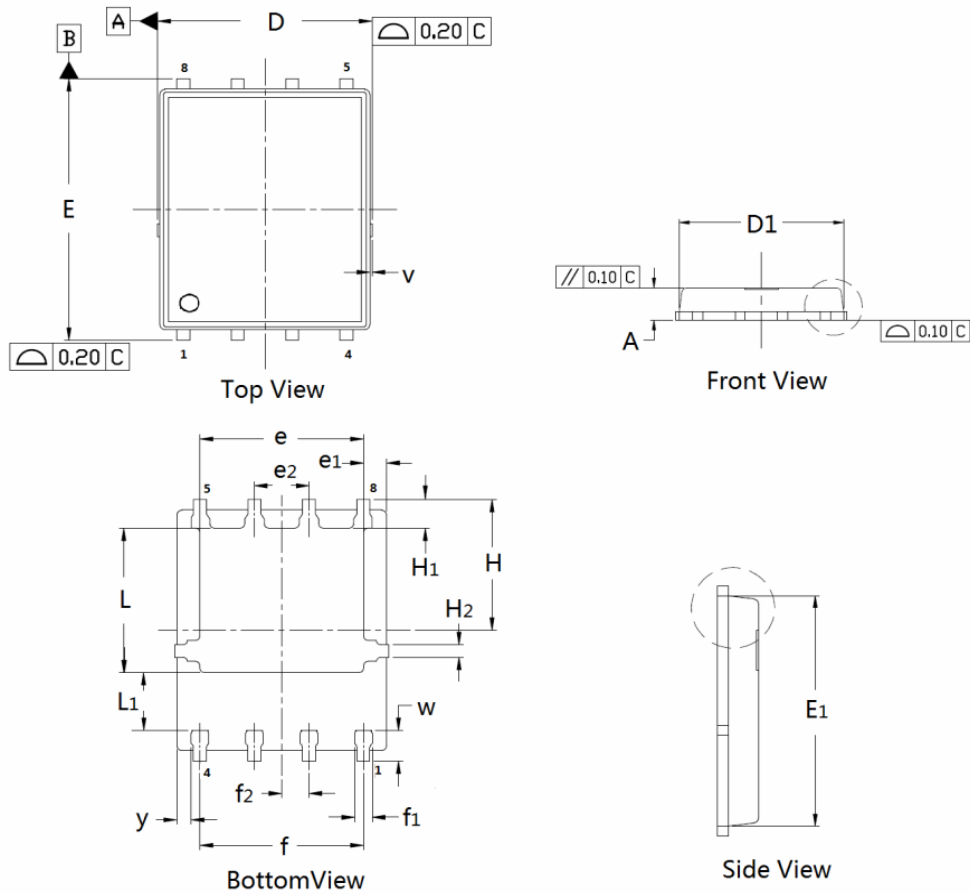
Safe operating area
 $-I_D=f(-V_{DS})$



Maximum Drain Current
 $-I_D=f(T_C)$



Max. transient thermal impedance
 $Z_{thJC}=f(t_p)$

P-Channel Enhancement Mode MOSFET
DFN5×6 Package Outline Data

DIMENSIONS (unit : mm)

Symbol	Typ	Max	Symbol	Min	Typ	Max
A	0.90	1.02	D	4.90	4.98	5.10
D ₁	4.80	4.89	E	5.90	6.11	6.25
E ₁	5.65	5.74	e	3.72	3.80	3.92
e ₁	--	0.5	e ₂	--	1.	--
f	--	3.8	f ₁	0.31	0.37	0.51
f ₂	--	0.6	H	--	3.	--
H ₁	0.59	0.63	H ₂	0.26	0.28	0.32
L	3.35	3.45	L ₁	--	1.	--
v	--	0.1	w	0.64	0.68	0.84
y	--	0.3		--		--